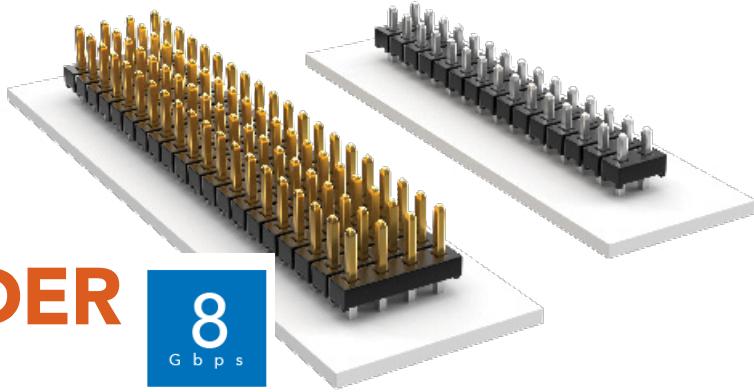


THROUGH-HOLE LOW PROFILE HEADER

(2.00 mm) .0787" PITCH • TMM SERIES

8
Gbps



TMM
Board Mates:
CLT, SQT, SQW, ESQT,
TLE, SMM, MMS

Cable Mates:
TCSD

TMM - **1** | **NO. PINS PER ROW**
02 thru 50

**LEAD
STYLE**
Specify
LEAD
STYLE
from
chart

**PLATING
OPTION**
-F = Gold flash
on post,
Matte Tin on tail
-L = 10 μ " (0.25 μ m)
Gold on post,
Matte Tin on tail
-T = Matte Tin

**ROW
OPTION**
-S = Single
Row
-D = Double
Row
-Q = Four
Row

**OTHER
OPTION**
-RA &
-RE
= Right-angle
(Lead Style
-01 only)
(2 positions
minimum,
-Q row)

-RC
= Retention Clip
(Mates with
TCSD)
(Double row only,
4 positions
minimum, only
available -06
lead style)

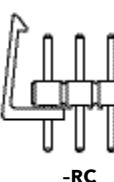
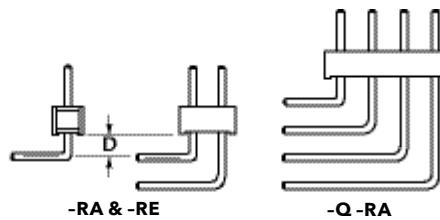
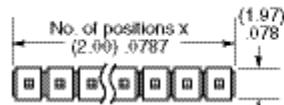
-XXX
= Polarized
Position
(Specify position
of omitted pin)

SPECIFICATIONS

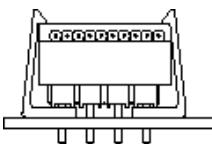
Insulator Material:
Black Liquid Crystal Polymer
Terminal Material:
Phosphor Bronze
Plating:
Sn or Au over
50 μ " (1.27 μ m) Ni
Operating Temp Range:
-55 °C to +105 °C with Tin;
-55 °C to +125 °C with Gold
Current Rating (SMM/TMM):
3.3 A per pin
(2 pins powered)
Voltage Rating:
281 VAC/397 VDC
mated with SQW;
250 VAC/354 VDC
mated with SQT
375 VAC/530 VDC
mated with SMM

PROCESSING

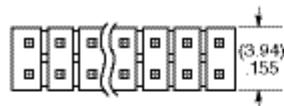
Lead-Free Solderable:
Yes



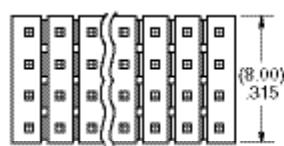
APPLICATION



Retention Clip Option (-RC)



| OPTION | D |
|--------|----------------|
| -RA | (1.27) .050 |
| -RE | (3.56) .140 |



| LEAD STYLE | A | B | C |
|---------------|----------------|----------------|----------------|
| -01 | | (3.20) .126 | (3.50) .138 |
| -02 | (8.20) .323 | (3.70) .146 | (3.00) .118 |
| -03 | | (4.00) .158 | (2.70) .106 |
| -04 | (5.69) .224 | (1.91) .075 | |
| -05 | (5.43) .214 | (1.65) .065 | (2.29) .090 |
| -06 | (9.58) .377 | (3.20) .126 | (4.88) .192 |

ALSO AVAILABLE

Contact Samtec

Other Platings



Note:
Some lengths, styles and
options are non-standard,
non-returnable.

